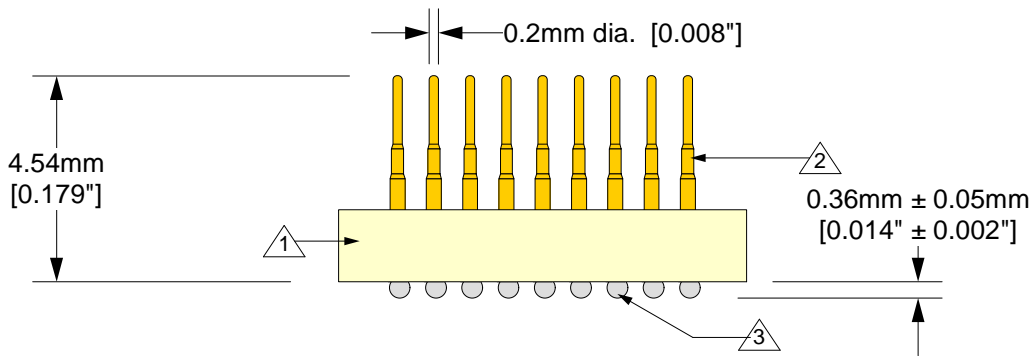


Top View



Side View


- 1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]
FR4/G10 or equivalent high temp material;
Non-clad
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- 3 Solder Balls: Sn96.5Ag3.0Cu0.5



Description: Giga-snaP BGA SMT Foot

105 position terminal pins (0.8mm centers, 9x12 array) to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA105A-B-61F Drawing		Status: Released	Scale: 6:1	Rev: B
 <p>© 2008 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	Drawing: J. Glab		Date: 01/04/08	
	File: SF-BGA105A-B-61F Dwg.mcd		Modified: 07/01/14	